



Material Content Data Sheet



Halogen-Free

Sales Product Name	TLS810B1LD V33	Issued	10. May 2021
MA#	MA001432038		
Package	PG-TSON-10-2	Weight*	31.71 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	0.996	3.14	3.14	31413	31413
leadframe	inorganic material	phosphorus	7723-14-0	0.003	0.01		105	
	non noble metal	zinc	7440-66-6	0.013	0.04		418	
	non noble metal	iron	7439-89-6	0.265	0.84		8368	
	non noble metal	copper	7440-50-8	10.773	33.98	34.87	339769	348660
wire	non noble metal	copper	7440-50-8	0.022	0.07	0.07	690	690
encapsulation	organic material	carbon black	1333-86-4	0.038	0.12		1185	
	plastics	epoxy resin	-	1.935	6.10		61035	
	inorganic material	silicondioxide	60676-86-0	16.815	53.04	59.26	530354	592574
leadfinish	non noble metal	tin	7440-31-5	0.370	1.17	1.17	11673	11673
plating	noble metal	silver	7440-22-4	0.064	0.20	0.20	2027	2027
glue	plastics	epoxy resin	-	0.103	0.32		3241	
	noble metal	silver	7440-22-4	0.308	0.97	1.29	9722	12963
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption.

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